

# PRESS RELEASE

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## **SABIC INTRODUCES NEW THERMOCOMP™ HMD-D SERIES OF HIGH MODULUS DUCTILE COMPOUNDS TO THE AMERICAS, EUROPE AT NPE 2018**

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SABIC, a global leader in the chemical industry, is introducing its next-generation THERMOCOMP™ HMD-D compounds to the Americas and Europe here at NPE 2018. Initially launched in Asia, these materials, on display at the company's booth (S19001), expand SABIC's THERMOCOMP portfolio of specialty compounds with high-performance, glass-reinforced polycarbonate (PC) materials. The new series of six grades delivers a unique combination of high modulus and ductility to enable lighter, thinner and stronger parts that advance design innovation and ease of use. They are engineered for challenging structural components in the consumer electronics, healthcare and transportation sectors.

"From smartphone cases to medical device housings and mass transit interior panels, there is an urgent need on the part of OEMs to replace metal and other traditional materials to reduce weight, expand design freedom and cut processing costs and complexity," said Joshua Chiaw, director of compounds at SABIC. "THERMOCOMP HMD-D compounds not only avoid the drawbacks of metal, they also add value with breakthrough ductility performance and excellent stiffness, which open opportunities for use in a wide range of structural applications. Based on enthusiastic and widespread adoption by our customers in Asia, we are expanding the availability of these materials to the Americas and Europe."

### **Balancing Ductility and Stiffness**

To achieve lighter weight and thinner geometries in structural applications, THERMOCOMP HMD-D compounds deliver high performance in key mechanical properties that previously were mutually exclusive. The materials offer both better ductility and dimensional stability/warpage control than other high-modulus PC-based materials. This distinctive combination of attributes allows, for example, the creation of thin-wall devices that may withstand stringent drop testing without cracking.

The new compounds use special glass fibers that minimize warpage. Grades with different glass fiber loadings (10 percent through 50 percent) are available to meet various modulus requirements.

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THERMOCOMP HMD-D products also deliver good strength for metal replacement while reducing weight due to their low specific gravity. They provide an excellent surface appearance by minimizing the floating of glass fibers to the surface and improved melt flow, which, unlike parts made with various competitive materials, are not affected by heat and moisture aging. Together with good color-matching capability and color stability, these characteristics help manufacturers appeal to fashion-conscious consumers of electronic devices and to patients who use home medical devices. All grades feature halogen-free flame retardancy to support sustainability efforts.

### **Optimizing Production**

The new THERMOCOMP HMD-D product family can help customers lower total system cost by supporting part integration, process simplification and potential elimination of secondary operations, such as painting. The materials' good flow and easy processing help reduce cycle times and boost productivity. In addition, these compounds have excellent thermal stability that allows them to be processed at a relatively high temperature.

Sample parts made with SABIC's THERMOCOMP HMD-D compounds are on display at the company's booth for the duration of NPE 2018.

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- High-resolution photos are available upon request.
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## ABOUT SABIC

SABIC is a global leader in diversified chemicals headquartered in Riyadh, Saudi Arabia. We manufacture on a global scale in the Americas, Europe, Middle East and Asia Pacific, making distinctly different kinds of products: chemicals, commodity and high performance plastics, agri-nutrients and metals.

We support our customers by identifying and developing opportunities in key end markets such as construction, medical devices, packaging, agri-nutrients, electrical and electronics, transportation and clean energy.

SABIC recorded a net profit of SR 18.4 billion (US\$ 4.9 billion) in 2017. Sales revenues for 2017 totaled SR 149.8 billion (US\$ 39.9 billion). Total assets stood at SR 322.5 billion (US\$ 86 billion) at the end of 2017. Production in 2017 stood at 71.2 million metric tons.

SABIC has more than 34,000 employees worldwide and operates in more than 50 countries. Fostering innovation and a spirit of ingenuity, we have 11,534 global patent filings, and have significant research resources with innovation hubs in five key geographies – USA, Europe, Middle East, South Asia and North Asia.

The Saudi Arabian government owns 70 percent of SABIC shares with the remaining 30 percent publicly traded on the Saudi stock exchange.

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## PHOTOS AND CAPTIONS



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